

SQF Technical Specification

ISO 9001:2008; ISO 14001:2004

Sidrabe Confidential

VACUUM DEPOSITION SYSTEM

SAF EM

Technical Specification

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1. Overview

Vacuum coater SAF EM is an R&D tool for deposition of various multifunctional coatings by magnetron sputtering and thermal evaporation methods. The substrate is 50x50 or 25x25mm solid, flat material that is suitable for vacuum coating. This equipment is designed for scientific research and development works.

Vacuum coater SAF EM is a single-chamber solution based on SAF multifunctional R&D cluster tool concept (http://www.sidrabe.com/cluster-tool).



2. Specification

2.1. Safety engineering

The coater is designed in accordance with ergonomic principles that ensure access to all parts of the coater for maintenance or replacement. All the equipment is suited for the specific processes within the limits of temperature, pressure and reactive medium requirements.

The coater is built in accordance with the safety regulations of the European Commission and European Standards:

- 2006/42/EC (Machinery Directive);
- 2006/95/EC (Low Voltage Directive);
- EN60204-1:2006+A1:2009 (Safety of Machinery).

The power supplies, electric components and the entire coater have CE marking.

2.2. Electric power

Frequency	50Hz/PEN
Voltage	3x400VAC
Power	10kW

2.3. Gases

Process gases Ar

Air pressure 0.5...0.7MPa

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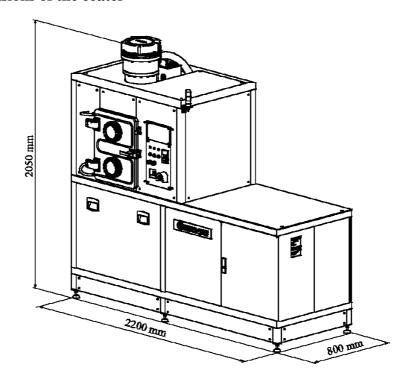
2.4. Water

Water inlet 10l/min (0.6m3/h) Water pressure 0.25...0.3MPa

2.5. Dimensions of the vacuum chamber (C-shaped stainless steel chamber)

Diameter, mm 520 Height, mm 700

2.6. Dimensions of the coater



2.7. Sample

2.7.1. Dimensions and properties of the sample

Material Glass, metal, or other solid, flat

sample, suitable for vacuum process

Dimensions, mm 25 x 25 and 50 x 50

Thickness, mm 1-20

Uncoated area, mm Up to 1.5 from each side

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2.7.2. Sampleholder

Material Copper (St.St., optional)

Dimensions, mm 84 x 84 x 1 (may be changed if

necessary)

2.8. Process chamber



2.8.1. Coating

Material for evaporation Au, Ag, Al,

Pd, Cu, Ni,

etc.

Material for magnetron

sputtering

oxides,

nitrides, carbon

Uniformity of the coating

± 5 %

2.8.2. Magnetron sputtering

Sputter magnetron 1 pc. Circular target \emptyset 2"

Changeable magnetron tilt

relative to the substrate

± 30 degrees

Power supply with match box

Gas feeding system

1 pc.

2.8.3. Thermal evaporation

Evaporator type Resistive evaporators

Evaporator quantity, pc 4 Shield quantity, pc. 1

Volume of crucible 1.2 cm³

Ultimate pressure, Torr 1x10⁻⁶

Base pressure, Torr $2x10^{-6}$

Process pressure, Torr $1x10^{-5}$

Evaporator power supply, pc. 1





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Evaporation temperature, °C Up to 1500

Distance from evaporator to the

center of the sample, mm

100...300

Boron nitride crucible, pc 5

Aluminum oxide crucible, pc 5

Quartz crucible, pc 5

Molybdenum boats (if boat

resistive evaporators are

included)

Wolfram boats (if boat resistive

evaporators are included)

20

20

2.8.4. Sample heater

Sample temperature, °C 200 deg MAX

Heater type IR heater

Heater qnty, pc. 1

Maximal heater output, W 500

Temperature measurement 1

device, pc.

2.8.5. Evaporation control

Quartz film thickness monitor, 2 (1 piece for 2 evaporators)

pc.

Quartz crystals for resonators, pc 10

Measurement precision, Å/s ≤ 0.1

2.9. Control

Pumping station is controlled by touch panel. Control of other equipment is manufacturer dependant.



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3. List of components

3.1.	Process	chamber		
	3.1.1.	Chamber d	oor with two view ports	1 pc.
	3.1.2.	Flanges wi	<u> </u>	4 pc.
	3.1.3.	Flanges wi	th optical window	2 pc.
	3.1.4.	_	lder, rotatable, for 1 sample with a possibility to	1 pc.
		place a mas		•
	3.1.5.	Thermal evaporator 4		
	3.1.6.	Sputter mag	gnetron (Gencoa)	1 pc.
	3.1.7.	Bdiscom 20	00RF AFP power supply with match box BDS	1 pc.
		AMN750		_
	3.1.8.	Gas feeding	g system	1 pc.
	3.1.9.	Quartz film	n thickness monitor	2 pc.
	3.1.10.	Sample hea	ater (optional)	
	3.1.11.	Air inlet va	alve	1 pc.
	3.1.12.	Pumping:		
		3.1.12.1.	Fore vacuum pump (DUO20 two-stage	
			mechanical pump (ISO KF 25), Pfeiffer	1 pc.
			Vacuum or similar from different	ı pc.
			manufacturer)	
		3.1.12.2.	Turbo pump (HiPace 700 turbomolecular	1 pc.
			pump DN 160 ISO-K, Pfeiffer Vacuum)	-
		3.1.12.3.	Filter DN 16	1 pc.
		3.1.12.4.	Silencer (ES 25S P/N109873, Alcatel)	1 pc.
		3.1.12.5.	Throttling valve (TBV-G-600-ISO-160, Nor-	1 pc.
			Cal)	
		3.1.12.6.	Pneumatic valve (GVMP-4001-CF, Nor-Cal)	1 pc.
		3.1.12.7.	EM Valve (XSA3-43S-5DZ-Q, 24 VDC,	2 pc.
			SMC)	_
		3.1.12.8.	Angle valve (XLAV-25J-A90LA-5LU, SMC)	2 pc.
		3.1.12.9.	Cold cathode vacuum sensor (KJLC 971,	1 pc.
			NW25 KF, Kurt J.Lesker)	_
		3.1.12.10.	Digital Pirani type vacuum sensor Digital	2 pc.
			Pirani sensor (PPT100 DN16 ISO-KF,	
		0.1.10.11	Pfeiffer Vacuum)	
		3.1.12.11.	Capacitance diaphragm vacuum gauge (100C	1 pc.
			Heated CDG 100-M11-NW1 (DN16 ISO-	
			KF) Nor-Cal)	

3.1.13. Inner lights